Contact Name Title - Contact Phone - Contact* Email - Contact*	PC SOCIATION CONNECTING ECTRONICS INDUSTRIES®	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2025-06-08 Contact Name Contact Name Contact Env-Stewards Contac	52-21.1					*						als and M	fg Informatio	on		
Title - Contact Phone - Contact* Phone - Contact* Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com	pplier Informa	ntion														
Product Name Product Enviro Compliance Phone - Contact* Product Enviro Compliance Phone - Representative* Product Enviro Compliance Phone - Representative* Product Enviro Compliance Phone - Representative* Product Enviro Compliance Product Enviro Compliance Phone - Representative* Product Enviro Compliance Product Enviro Stewards © onsemi.com	Company name*				Company unique ID			Unique ID Authority					Response Date*			
Product Env-Stewards Uthorized Representative* Title - Representative Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards © onsemi.com NA Product Env-Stewards © onsemi.com NA Product Env-Stewards © onsemi.com NA Nanufacturing Site Weight* UOM NPN/5A/60V TO-126 2025-06-08 CP8 837.057 mg In anufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy NA Product-Env-Stewards © onsemi.com NA Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Proccess Information Terminal Plating / Grid Array Material Nanufacturing Proccess Information Terminal Plating / Grid Array Material Nanufacturing Proccess Body Temperature Nanufacturing Nanufacturing Number of Reflow Cycles Nanufacturing Peak Process Body Temperature Nanufacturing Nanufacturing Number of Reflow Cycles Nanufacturing Nanu	onsemi												2025-06-08			
Title - Representative Phone - Representative Phone - Representative Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards ©nsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM KSD1691GSTU NPN/5A/60V TO-126 2025-06-08 CP8 837.057 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Mate Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	ntact Name			Title - Contact			I	Phone - Contact*					Email - Contact*			
Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM Description: Weight* Weight* Womanufacturing Site Weight* Womanufacturing Site Weight* Weight* Womanufacturing Process Information CP8 Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds Seconds Annufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy NA O C 30 Seconds 3	Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*				
KSD1691GSTU NPN/5A/60V TO-126 2025-06-08 CP8 837.057 mg Instituting Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	Requester	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date	e Ver	sion	Manufacturing Site		,	Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3			KSD1691	1GSTU	NPN/5A/60V TO-	126		2025-06-08			CP8		8	337.057	mg	Each
Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3				. 15		GED 020 Mg		D 1 D		1	1.6		T		CD CL	1
Patter III (bi) dimensed Co IIIo) III	, , , , , , , , , , , , , , , , , , ,						L Rating	<u> </u>		ime at Peak	T .		er of Reflow Cyc	cles		
omments	<u> </u>	(Sn) - annealed	C	CU Alloy	l N	NA		U		[C	30		secon	ds 3		
	mments															
or more information regarding material composition please refer to page 3			•.•	1 6 .												

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belie as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applica										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).								
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight Unit of Measure Level Substance		Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.38	mg	Supplier Silicon (Si)		7440-21-3		0.38	mg
Die Attach	0.229	mg	Supplier	Silver (Ag)	7440-22-4		0.0034	mg
			A	Lead (Pb)	7439-92-1	7a	0.2141	mg
			Supplier	Tin (Sn)	7440-31-5		0.0115	mg
Lead Frame	362.5	mg	Supplier	Iron (Fe)	7439-89-6		0.3625	mg
			Supplier	Copper (Cu)	7440-50-8		362.0287	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1087	mg
Mold Compound-Black	461.72	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		1.3852	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		4.6172	mg
			Supplier	Carbon Black (C)	1333-86-4		5.5406	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		78.4924	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		55.4064	mg
			Supplier	Silica (SiO2)	14464-46-1		2.3086	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		36.9376	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		277.032	mg
Plating	12.12	mg	Supplier	Tin (Sn)	7440-31-5		12.12	mg
Wire Bond - Au	0.108	mg	Supplier	Gold (Au)	7440-57-5		0.108	mg